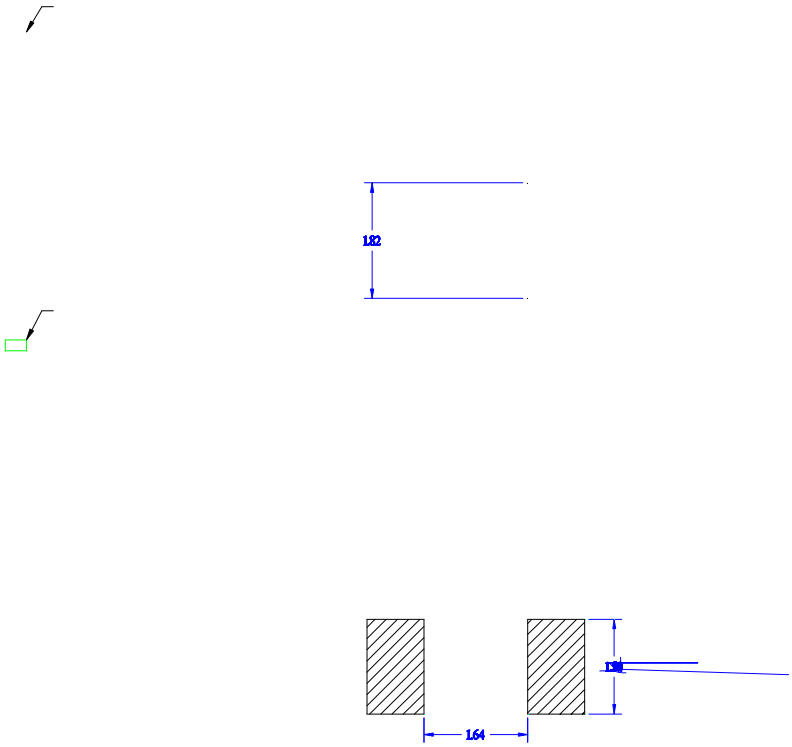
Features

Pb free product—RoHS compliant
Low power consumption, High efficiency
Reliable and rugged
Long life – solid state reliability
Radiant angle: 70°

Package Dimension



Recommended Soldering patterns

Part NO.	Chip Material	Lens Color
SL-T4233IRC050-L365-850	AlGaAs/Si	Water Clear

Notes:

1. All dimensions are in millimeters.
2. Tolerance is ±0.10mm unless otherwise noted
3. Specifications are subject to change without notice.

Absolute Maximum Ratings at Ta=25

Parameter	MAX.	Unit
Power Dissipation	150	mW
Continuous Forward Current	100	mA
Peak Forward Current[*3]	1.0	A
Reverse Voltage	5	V
Electrostatic Discharge (HBM)[*5]	2000	V
Moisture Sensitivity Level[*1]	5a	
Operating Temperature	-40 to + 85	
Storage Temperature	-40 to + 100	
IR Reflow Temperature[*4]	260 for 10 Seconds MAX.	

1. **Storage and operating:**

(1). Storage requirements before vacuum bag opened: Temperature<30 , Humidity<65%RH;

(2). Check air leakage and vacuum bag damage before opened. If there is any issue found, check the humidity indicator card immediately after bag opened:

a. If color changes on “10% circle” of the humidity indicator card only and not the circles of 20% and above, components can be used without additional handling;

b. If color changes on both 10% and 20% circles but not the circles of 30% and above, components must be dehumidified according to the conditions of bullet (5);

c. If color changes on 10%, 20%, and 30% circle or above, the product should be returned to the supplier for high temperature dehumidification;

(3). After bag opened, manual soldering or reflow process must follow the following requirements:

a. Complete soldering / reflow within 24 hours;

b. Requirements of working environment: Temperature<30 , Humidity<60%RH;

(4). If the working condition is outside (3)a or (3)b requirement, the components must be dehumidified according to the conditions of bullet (5);

(5). Low temperature dehumidification: temperature 60±5 , at least 24 hours;

(6). Shelf life: 30 days. If it’s over 30 days from the production date on the package label, the components must be dehumidified according to the condition of bullet (5). If customer is unable to dehumidify, return components to LIGHT for dehumidification.

2. **Cleaning:**

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED if necessary.

3. **Peak Forward Current:**

Condition for is IFP pulse: Pulse Width≤100μs and duty≤1%.

4. **IR Reflow Temperature:**

It is the Plate Temperature.

5. **Caution in ESD:**

Static Electricity and surge damages the LED. It is recommend to use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

Infrared Emitting Diode Specification

●Commodity: Infrared emitting diode

●Radiant Intensity Bin Limits (At 50mA)

BIN CODE	Min.(mW/sr)	Max. (mW/sr)
15	37.5	45
16	45	54
17	54	64.8
18	64.8	77.76
19	77.76	93.3

NOTE: The Ie guarantee should be added ±15% tolerance.

Label Explanation